Panasonic
BUSINESS

2020

Plasma Processing Equipment catalog

Dry Etcher

Model ID

APX300 (Option S)

Model No.NM-EFE3AA-S

max.Φ8 inch single wafer system

- APX300(Option S) can process wafers such as power devices, SAW filters, communication devices and MEMS sensors etc.. inherited from previous best seller model E620 by using same single wafer process chamber.
- “MSC-ICP(Multi spiral coil type ICP)” source is the latest technology to realize highly accurate processing. In addition, “BM-ICP(Beamed type ICP)” option with higher electron density performs faster processing , covering wide range of process demand.
- Two types of handling system :
  “ Atmospheric loading supply ” and “ Vacuum load lock supply ”
- CE certificated

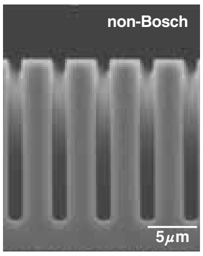
Model ID	APX300
Model No.	NM-EFE3AA-S
Plasma source	ICP Plasma
Process gas	Standard 4 lines（Maximum 6 Lines: Chlorinated Gas, Fluoride Gas, Ar, O_2, He, etc.)
Wafer size *1	ϕ100 ㎜/ 150 ㎜ wafer with orientation flat ϕ200 ㎜ wafer with notch
Dimensions (㎜)	【Load lock wafer Handling】 W 1 350 × D 2 230 × H 2 000 (Exclude touch panel, operation section and signal tower)
	【Load lock wafer Handling】 W 1 375 × D 2 600 × H 2 000 (Exclude touch panel, operation section and signal tower)
Mass	2 000 ㎏ (Differs depending on machine configuration)
Power source *2	3-phase AC 200 / 208 / 220 / 230 / 240 ±10 V、50 / 60 Hz、21.00 kVA
Pneumatic source	0.5 MPa to 0.7 MPa, 250 L/min (A.N.R.)
N_2 Source	0.1 MPa to 0.2 MPa, 50 L/min (A.N.R.)

*Details should be referred to Spec.

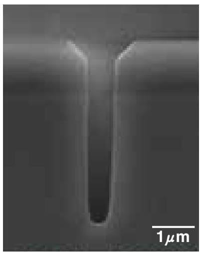
*1 : Please consult , if different size of wafer will be required.
*2 : 3-phase electricity has two kinds of lineage. Figure shows total.

Various process options available inherited from previous best seller model E620

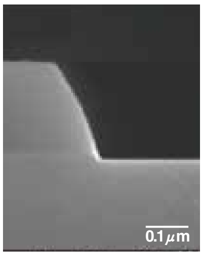
Power devices (Si, SiC, GaN)



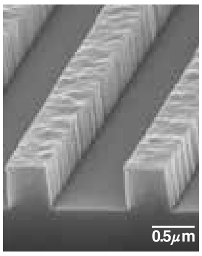
Si trench



SiC trench

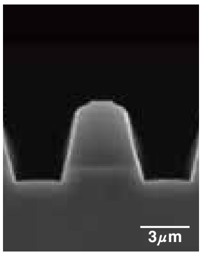


AlGaN recess

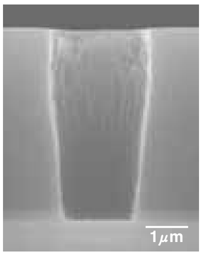


Poly-Si gate

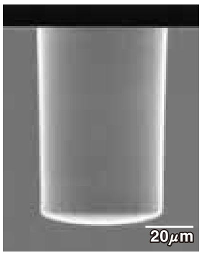
SAW・Communication devices



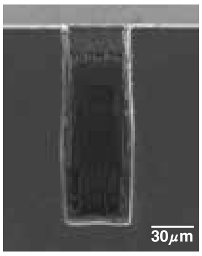
LN substrate
(LiNbOx)



Low-k contact

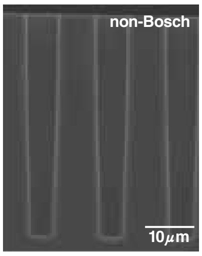


GaAs via

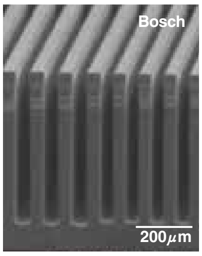


SiC via

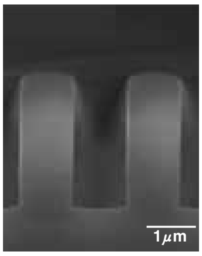
MEMS・Sensors



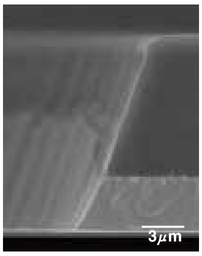
TSV



Si deep etching

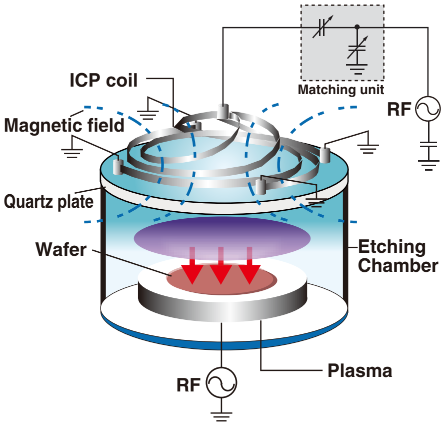


SiO_2

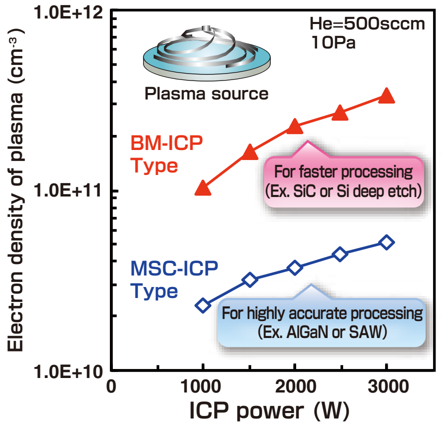


PZT layer
(future)

Process Chamber and Two Types of Plasma Sources

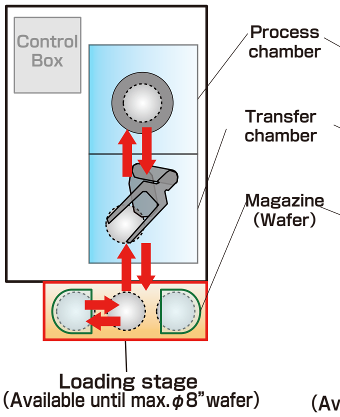


Process chamber with MSC-ICP

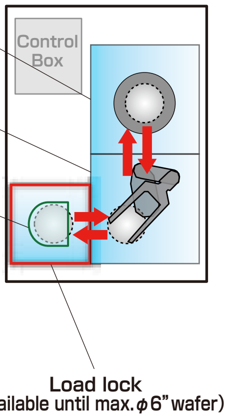


Plasma source and electron density

Two Types of Handling System



Atmospheric loading supply



Vacuum load lock supply

⚠Safety Cautions

●Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.	●To ensure safety when using this equipment, all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instruction manual thoroughly.

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●Changes in specifications and appearance may be made without notice for product improvement.
●Homepage industrial.panasonic.com/ww/fa-jisso

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